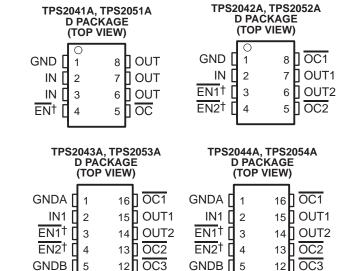


- 500 mA Continuous Current Per Channel
- Independent Thermal and Short-Circuit Protection With Overcurrent Logic Output
- Operating Range . . . 2.7 V to 5.5 V
- CMOS- and TTL-Compatible Enable Inputs
- 2.5-ms Typical Rise Time
- Undervoltage Lockout
- 10 μA Maximum Standby Supply Current for Single and Dual (20 μA for Triple and Quad)
- Bidirectional Switch
- Ambient Temperature Range, 0°C to 85°C
- ESD Protection
- UL Listed File No. E169910

# description

The TPS2041A through TPS2044A and TPS2051A through TPS2054A power-distribution switches are intended for applications where



 $\ensuremath{^{\dagger}}$  All enable inputs are active high for the TPS205xA series. NC - No connect

IN2

EN4†

6

7

8

11 OUT3

10 **□** OUT4

OC4

11 OUT3

10 NC

9∏NC

heavy capacitive loads and short circuits are likely to be encountered. These devices incorporate  $80\text{-m}\Omega$  N-channel MOSFET high-side power switches for power-distribution systems that require multiple power switches in a single package. Each switch is controlled by an independent logic enable input. Gate drive is provided by an internal charge pump designed to control the power-switch rise times and fall times to minimize current surges during switching. The charge pump requires no external components and allows operation from supplies as low as 2.7 V.

IN2

EN3†

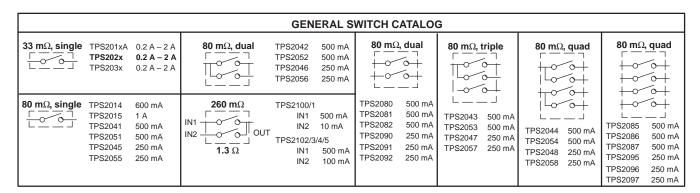
NC

6

7

8

When the output load exceeds the current-limit threshold or a short is present, these devices limit the output current to a safe level by switching into a constant-current mode, pulling the overcurrent  $(\overline{OCx})$  logic output low. When continuous heavy overloads and short circuits increase the power dissipation in the switch, causing the junction temperature to rise, a thermal protection circuit shuts off the switch to prevent damage. Recovery from a thermal shutdown is automatic once the device has cooled sufficiently. Internal circuitry ensures the switch remains off until valid input voltage is present. These power-distribution switches are designed to current limit at 0.9 A.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



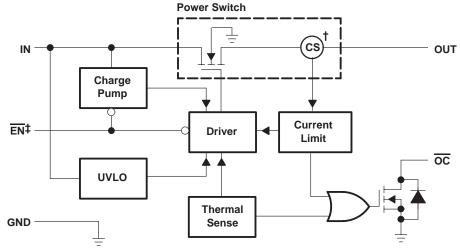
#### **AVAILABLE OPTIONS**

		RECOMMENDED MAXIMUM CONTINUOUS	TYPICAL SHORT-CIRCUIT	NUMBER OF	PACKAGED DEVICES
TA	ENABLE	LOAD CURRENT (A)	CURRENT LIMIT AT 25°C (A)	SWITCHES	SOIC (D)†
	Active low	0.5		Single	TPS2041AD
	Active high		0.9	Sirigle	TPS2051AD
	Active low			Dual	TPS2042AD
0°C to 85°C	Active high			Duai	TPS2052AD
0.0 10 92.0	Active low			Triplo	TPS2043AD
	Active high			Triple	TPS2053AD
	Active low			Ound	TPS2044AD
	Active high			Quad	TPS2054AD

<sup>†</sup>The D package is available taped and reeled. Add an R suffix to device type (e.g., TPS2041ADR)

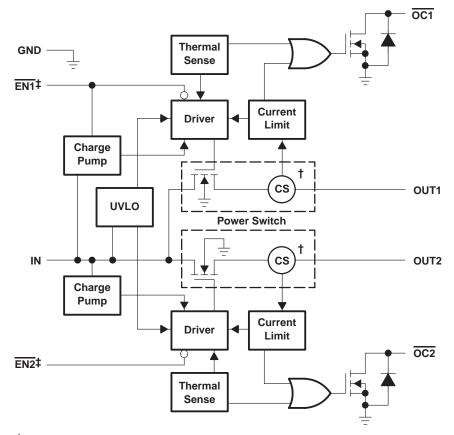
# functional block diagrams

# **TPS2041A**



- † Current sense
- ‡ Active high for TPS205xA series

#### **TPS2042A**

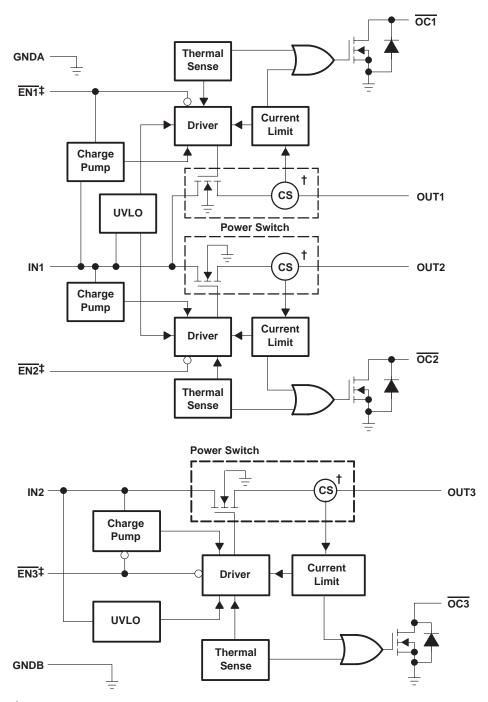


- † Current sense
- ‡ Active high for TPS205xA series



# functional block diagrams

#### **TPS2043A**

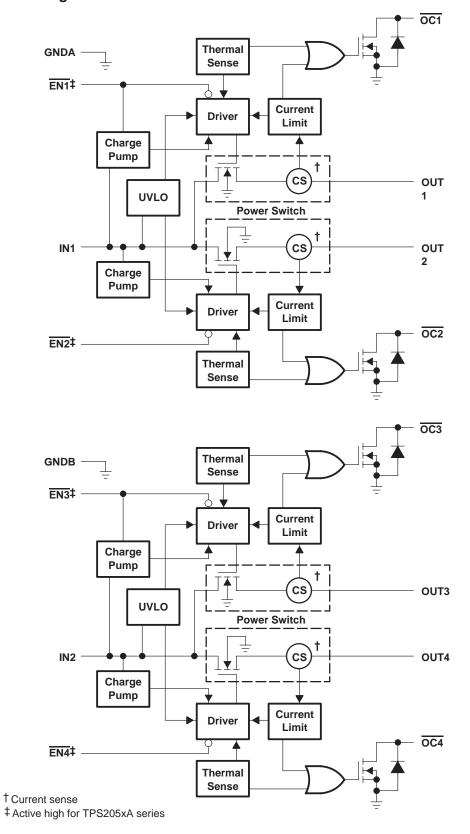


- † Current sense
- ‡ Active high for TPS205xA series



# functional block diagrams

#### **TPS2044A**





SLVS247 – SEPTEMBER 2000

#### **Terminal Functions**

# TPS2041A and TPS2051A

	TERMINAL	TERMINAL					
NAME NO.		0.	1/0	DESCRIPTION			
INAIVIE	TPS2041A	TPS2051A					
EN	4	-	1	Enable input. Logic low turns on power switch.			
EN	- 4		- 1	Enable input. Logic high turns on power switch.			
GND	1	1	- 1	Ground			
IN	2, 3	2, 3	-1	Input voltage			
OC	5	5	0	Overcurrent. Logic output active low			
OUT	JT 6, 7, 8 6, 7, 8		0	Power-switch output			

# TPS2042A and TPS2052A

	TERMINAL	_						
NAME	N	0.	1/0	DESCRIPTION				
	TPS2042A	TPS2052A						
EN1	3	-	-1	Enable input. Logic low turns on power switch, IN-OUT1.				
EN2	4	-	- 1	Enable input. Logic low turns on power switch, IN-OUT2.				
EN1	ı	3	- 1	Enable input. Logic high turns on power switch, IN-OUT1.				
EN2	ı	4	1	Enable input. Logic high turns on power switch, IN-OUT2.				
GND	1	1	1	Ground				
IN	2	2	1	Input voltage				
OC1	8	8	0	Overcurrent. Logic output active low, for power switch, IN-OUT1				
OC2	5	5	0	Overcurrent. Logic output active low, for power switch, IN-OUT2				
OUT1	7	7	0	Power-switch output				
OUT2	6	6	0	Power-switch output				



# **Terminal Functions (Continued)**

# TPS2043A and TPS2053A

	TERMINAL	-		
NAME	N	0.	1/0	DESCRIPTION
NAME	TPS2043A	TPS2053A	1	
EN1	3	-	ı	Enable input, logic low turns on power switch, IN1-OUT1.
EN2	4	_	I	Enable input, logic low turns on power switch, IN1-OUT2.
EN3	7	ı	I	Enable input, logic low turns on power switch, IN2-OUT3.
EN1	_	3	1	Enable input, logic high turns on power switch, IN1-OUT1.
EN2	_	4	I	Enable input, logic high turns on power switch, IN1-OUT2.
EN3	_	7	1	Enable input, logic high turns on power switch, IN2-OUT3.
GNDA	1	1		Ground for IN1 switch and circuitry.
GNDB	5	5		Ground for IN2 switch and circuitry.
IN1	2	2	I	Input voltage
IN2	6	6	I	Input voltage
NC	8, 9, 10	8, 9, 10		No connection
OC1	16	16	0	Overcurrent, logic output active low, IN1-OUT1
OC2	13	13	0	Overcurrent, logic output active low, IN1-OUT2
OC3	12	12	0	Overcurrent, logic output active low, IN2-OUT3
OUT1	15	15	0	Power-switch output, IN1-OUT1
OUT2	14	14	0	Power-switch output, IN1-OUT2
OUT3	11	11	0	Power-switch output, IN2-OUT3

# TPS2044A and TPS2054A

	TERMINAL	_		
NAME	N(	0.	1/0	DESCRIPTION
	TPS2044A	TPS2054A		
EN1	3	-	ı	Enable input. logic low turns on power switch, IN1-OUT1.
EN2	4	1	I	Enable input. Logic low turns on power switch, IN1-OUT2.
EN3	7	ı	I	Enable input. Logic low turns on power switch, IN2-OUT3.
EN4	8	-	1	Enable input. Logic low turns on power switch, IN2-OUT4.
EN1	_	3	1	Enable input. Logic high turns on power switch, IN1-OUT1.
EN2	-	4	ı	Enable input. Logic high turns on power switch, IN1-OUT2.
EN3	_	7	1	Enable input. Logic high turns on power switch, IN2-OUT3.
EN4	-	8	ı	Enable input. Logic high turns on power switch, IN2-OUT4.
GNDA	1	1		Ground for IN1 switch and circuitry.
GNDB	5	5		Ground for IN2 switch and circuitry.
IN1	2	2	- 1	Input voltage
IN2	6	6	ı	Input voltage
OC1	16	16	0	Overcurrent. Logic output active low, IN1-OUT1
OC2	13	13	0	Overcurrent. Logic output active low, IN1-OUT2
OC3	12	12	0	Overcurrent. Logic output active low, IN2-OUT3
OC4	9	9	0	Overcurrent. Logic output active low, IN2-OUT4
OUT1	15	15	0	Power-switch output, IN1-OUT1
OUT2	14	14	0	Power-switch output, IN1-OUT2
OUT3	11	11	0	Power-switch output, IN2-OUT3
OUT4	10	10	0	Power-switch output, IN2-OUT4



SLVS247 - SEPTEMBER 2000

## detailed description

# power switch

The power switch is an N-channel MOSFET with a maximum on-state resistance of 135 m $\Omega$  ( $V_{I(IN)}$  = 5 V). Configured as a high-side switch, the power switch prevents current flow from OUT to IN and IN to OUT when disabled. The power switch supplies a minimum of 500 mA per switch.

#### charge pump

An internal charge pump supplies power to the driver circuit and provides the necessary voltage to pull the gate of the MOSFET above the source. The charge pump operates from input voltages as low as 2.7 V and requires very little supply current.

#### driver

The driver controls the gate voltage of the power switch. To limit large current surges and reduce the associated electromagnetic interference (EMI) produced, the driver incorporates circuitry that controls the rise times and fall times of the output voltage. The rise and fall times are typically in the 2-ms to 4-ms range.

## enable (ENx, ENx)

The logic enable disables the power switch and the bias for the charge pump, driver, and other circuitry to reduce the supply current. The supply current is reduced to less than 10  $\mu$ A on the single and dual devices (20  $\mu$ A on the triple and quad devices) when a logic high is present on  $\overline{ENx}$  (TPS204xA<sup>†</sup>) or a logic low is present on  $\overline{ENx}$  (TPS205xA<sup>†</sup>). A logic zero input on  $\overline{ENx}$  or a logic high on  $\overline{ENx}$  restores bias to the drive and control circuits and turns the power on. The enable input is compatible with both TTL and CMOS logic levels.

## overcurrent (OCx)

The  $\overline{OCx}$  open-drain output is asserted (active low) when an overcurrent or overtemperature condition is encountered. The output will remain asserted until the overcurrent or overtemperature condition is removed.

#### current sense

A sense FET monitors the current supplied to the load. The sense FET measures current more efficiently than conventional resistance methods. When an overload or short circuit is encountered, the current-sense circuitry sends a control signal to the driver. The driver in turn reduces the gate voltage and drives the power FET into its saturation region, which switches the output into a constant-current mode and holds the current constant while varying the voltage on the load.

#### thermal sense

The TPS204xA and TPS205xA implement a dual-threshold thermal trip to allow fully independent operation of the power distribution switches. In an overcurrent or short-circuit condition the junction temperature rises. When the die temperature rises to approximately 140°C, the internal thermal sense circuitry checks to determine which power switch is in an overcurrent condition and turns off that switch, thus isolating the fault without interrupting operation of the adjacent power switch. Hysteresis is built into the thermal sense, and after the device has cooled approximately 20 degrees, the switch turns back on. The switch continues to cycle off and on until the fault is removed. The (OCx) open-drain output is asserted (active low) when overtemperature or overcurrent occurs.

#### undervoltage lockout

A voltage sense circuit monitors the input voltage. When the input voltage is below approximately 2 V, a control signal turns off the power switch.

T Product series designations TPS204x and TPS205x refer to devices presented in this data sheet and not necessarily to other TI devices numbered in this sequence.



SLVS247 – SEPTEMBER 2000

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input voltage range, V <sub>I(IN)</sub> (see Note 1)	0.3 V to 6 V
Output voltage range, VO(OUT) (see Note 1)	
Input voltage range, V <sub>I(ENx)</sub> or V <sub>I(ENx)</sub>	
Continuous output current, IO(OUT)	linternally limited
Continuous total power dissipation	See Dissipation Rating Table
Operating virtual junction temperature range, T <sub>J</sub>	0°C to 125°C
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C
Lead temperature soldering 1,6 mm (1/16 inch) from case for 10 seconds	
Electrostatic discharge (ESD) protection: Human body model MIL-STD-883C	2 kV
Machine model	0.2 kV

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### NOTE 1: All voltages are with respect to GND.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
D-8	725 mW	5.9 mW/°C	464 mW	377 mW
D-16	1123 mW	9 mW/°C	719 mW	584 mW

## recommended operating conditions

	MIN	MAX	UNIT
Input voltage, V <sub>I(IN)</sub>	2.7	5.5	V
Input voltage, V <sub>I(EN)</sub> or V <sub>I(EN)</sub>	0	5.5	V
Continuous output current, IO(OUT) (per switch)	0	500	mA
Operating virtual junction temperature, T <sub>J</sub>	0	125	°C



SLVS247 - SEPTEMBER 2000

electrical characteristics over recommended operating junction temperature range,  $V_{I(IN)}$ = 5.5 V,  $I_O$  = rated current,  $V_{I(EN)} = 0$  V,  $V_{I(EN)} = V_{I(IN)}$  (unless otherwise noted)

#### power switch

	DADAMETED	TEST 00	NOTIONST	TF	PS204x	4	TPS205xA			LINUT
	PARAMETER	TEST CO	NDITIONST	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
		$V_{I(IN)} = 5 \text{ V},$ $I_{O} = 0.5 \text{ A}$	T <sub>J</sub> = 25°C,		80	100		80	100	
rDS(on)	Static drain-source on-state resistance, 5-V operation	$V_{I(IN)} = 5 \text{ V},$ $I_{O} = 0.5 \text{ A}$	T <sub>J</sub> = 85°C,		90	120		90	120	
		V <sub>I(IN)</sub> = 5 V, I <sub>O</sub> = 0.5 A	T <sub>J</sub> = 125°C,		100	135		100	135	mΩ
		$V_{I(IN)} = 3.3 \text{ V},$ $I_{O} = 0.5 \text{ A}$	T <sub>J</sub> = 25°C,		90	125		90	125	
	Static drain-source on-state resistance, 3.3-V operation	$V_{I(IN)} = 3.3 \text{ V},$ $I_{O} = 0.5 \text{ A}$	T <sub>J</sub> = 85°C,		110	145		110	145	
		$V_{I(IN)} = 3.3 \text{ V},$ $I_{O} = 0.5 \text{ A}$	T <sub>J</sub> = 125°C,		120	160		120	160	
	Rise time, output	$V_{I(IN)} = 5.5 \text{ V},$ $C_L = 1 \mu\text{F},$	$T_J = 25^{\circ}C$ , $R_L=10 \Omega$		2.5			2.5		ms
t <sub>r</sub>	Kise time, output	$V_{I(IN)} = 2.7 \text{ V},$ $C_L = 1 \mu\text{F},$	$T_J = 25^{\circ}C$ , $R_L=10 \Omega$		3			3		1115
	Fall time, output	$V_{I(IN)} = 5.5 \text{ V},$ $C_L = 1 \mu\text{F},$	$T_J = 25^{\circ}C$ , $R_L=10 \Omega$	4.4				4.4		mo
tf		$V_{I(IN)} = 2.7 \text{ V},$ $C_L = 1 \mu\text{F},$	$T_J = 25^{\circ}C$ , $R_L=10 \Omega$		2.5			2.5		ms

<sup>†</sup> Pulse-testing techniques maintain junction temperature close to ambient temperature; thermal effects must be taken into account separately.

# enable input ENx or ENx

	PARAMETER		TEST CONDITIONS	TPS204xA			TPS205xA			UNIT
			TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONT
VIH	High-level input v	roltage	$2.7 \text{ V} \le \text{V}_{\text{I(IN)}} \le 5.5 \text{ V}$	2			2			V
V <sub>II</sub> Low-level input voltage		oltogo	$4.5 \text{ V} \le \text{V}_{\text{I(IN)}} \le 5.5 \text{ V}$			0.8			0.8	V
VIL	Low-level input vi	onage	2.7 V≤ V <sub>I(IN)</sub> ≤ 4.5 V			0.4			0.4	
Ţ.,	Innuit ourrent	TPS204xA	$V_{I}(\overline{ENx}) = 0 \ V \text{ or } V_{I}(\overline{ENx}) = V_{I}(IN)$	-0.5	-0.5 0.5					
'	Input current	TPS205xA	$V_{I(ENx)} = V_{I(IN)}$ or $V_{I(ENx)} = 0$ V				-0.5		0.5	μΑ
ton	on Turnon time		$C_L = 100  \mu F, R_L = 10  \Omega$			20			20	ms
t <sub>off</sub>	Turnoff time		$C_L = 100  \mu F, R_L = 10  \Omega$			40			40	

#### current limit

PARAMETER		TEST CONDITIONS <sup>†</sup>	Т	PS204x <i>A</i>	٨	TPS205xA			UNIT
		TEST CONDITIONS <sup>†</sup>	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
los	Short-circuit output current	V <sub>I(IN)</sub> = 5 V, OUT connected to GND, Device enabled into short circuit	0.7	1	1.3	0.7	1	1.3	А

<sup>†</sup> Pulse-testing techniques maintain junction temperature close to ambient temperature; thermal effects must be taken into account separately.



electrical characteristics over recommended operating junction temperature range,  $V_{I(IN)} = 5.5 \text{ V}$ ,  $I_{O} = \text{rated current}$ ,  $V_{I(EN)} = 0 \text{ V}$ ,  $V_{I(EN)} = V_{I(IN)}$  (unless otherwise noted) (continued)

# supply current (TPS2041A, TPS2051A)

PARAMETER		TEST CONDIT	IONE	Т	PS2041	Α .	TI	UNIT				
PARAMETER		TEST CONDITIONS				MAX	MIN	TYP	MAX			
				_	T <sub>J</sub> = 25°C		0.025	1				
Supply current, low-level output	No Load	$V_{I}(\overline{EN}) = V_{I}(IN)$	$-40^{\circ}\text{C} \le \text{T}_{\text{J}} \le 125^{\circ}\text{C}$			10						
	on OUT	V O. V	T <sub>J</sub> = 25°C					0.025	1	μΑ		
		VI(EN) = 0 V	$-40^{\circ}\text{C} \le \text{T}_{J} \le 125^{\circ}\text{C}$						10	1 1		
	No Load on OUT			., — .,,	T <sub>J</sub> = 25°C		85	110				
Supply current,		$V_{I}(\overline{EN}) = 0 V$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$		100					μА		
high-level output			T <sub>J</sub> = 25°C					85	110			
		VI(EN) = VI(IN)	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$					100				
Lookago ourrant	OUT	$V_{I(EN)} = V_{I(IN)}$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$		100							
Leakage current	connected to ground	V <sub>I(EN)=0</sub> V	-40°C ≤ T <sub>J</sub> ≤ 125°C			100		μΑ				
Poverse leekage ourrent	IN = High	$V_{I}(EN) = 0 V$	T <sub>J</sub> = 25°C		0.3							
Reverse leakage current	impedance	$V_{I(EN)} = V_{I(IN)}$	7 1J = 20 C					0.3		μΑ		

# supply current (TPS2042A, TPS2052A)

PARAMETER		TEST CONDIT	IONE	TPS2042A			TPS2052A			UNIT
		1EST CONDIT	TEST CONDITIONS			MAX	MIN	TYP	MAX	ONIT
Supply current, low-level output			T <sub>J</sub> = 25°C		0.025	1				
	No Load	$V_{I}(\overline{ENx}) = V_{I}(IN)$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$			10				μΑ
	on OUT	V.(=\) = 0 \/	T <sub>J</sub> = 25°C			0.02	0.025	1	μΑ	
		$V_{I(ENx)} = 0 V$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$						10	
Supply current, high-level output			T <sub>J</sub> = 25°C		85	110				
	No Load	$V_{I}(\overline{ENx}) = 0 V$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$		100					
	on OUT	Variation Variation	T <sub>J</sub> = 25°C					85	110	μΑ
		$V_{I(ENx)} = V_{I(IN)}$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$					100		
Leakage current	OUT connected to ground	$V_{I}(\overline{ENx}) = V_{I}(IN)$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$		100					
		V <sub>I(ENx)</sub> = 0 V	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$					100		μΑ
Reverse leakage current	IN = high	$V_{I(EN)} = 0 V$	T <sub>J</sub> = 25°C		0.3					
	impedance	impedance	$V_{I(EN)} = V_{I(IN)}$	717=250			·		0.3	

SLVS247 - SEPTEMBER 2000

electrical characteristics over recommended operating junction temperature range,  $V_{I(IN)} = 5.5 \text{ V}$ ,  $I_{O} = \text{rated current}$ ,  $V_{I(EN)} = 0 \text{ V}$ ,  $V_{I(EN)} = V_{I(IN)}$  (unless otherwise noted) (continued)

# supply current (TPS2043A, TPS2053A)

PARAMETER	TEST CONDITIONS		TPS2043A			TPS2053A			UNIT	
PARAMETER	TEST CONDITIONS				TYP	MAX	MIN	TYP	MAX	UNII
Supply current, low-level output			T <sub>J</sub> = 25°C		0.05	2				
	No Load	$V_{I}(\overline{ENx}) = V_{I}(INx)$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$			20				
	on OUTx	VI(ENx) = 0 V	T <sub>J</sub> = 25°C					0.05	2	μΑ
			$-40^{\circ}C \le T_{J} \le 125^{\circ}C$						20	
		$V_{I}(\overline{ENx}) = 0 V$	T <sub>J</sub> = 25°C		160	200				
Supply current,	No Load		$-40^{\circ}C \le T_{J} \le 125^{\circ}C$		200					
high-level output	on OUTx	$V_{I(ENx)} = V_{I(INx)}$	T <sub>J</sub> = 25°C					160	200	μΑ
			-40°C ≤ T <sub>J</sub> ≤ 125°C					200		
Leakage current	OUTx connected to ground	$V_{I}(\overline{ENx}) = V_{I}(INx)$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$		200					
		$V_{I(ENx)} = 0 V$	$-40^{\circ}C \le T_{J} \le 125^{\circ}C$					200		μΑ
Reverse leakage	IN = high	$V_{I}(\overline{ENx}) = 0 V$	T 25°C		0.3					
current	impedance	$V_{I(ENx)} = V_{I(IN)}$	T <sub>J</sub> = 25°C					0.3		μΑ

# supply current (TPS2044A, TPS2054A)

PARA-	TEST CONDITIONS		TPS2044A			TF	UNIT			
METER		TEST CONDITIONS			TYP	MAX	MIN	TYP	MAX	ONT
1 - 11 2 - 1 - 2		l	T <sub>J</sub> = 25°C		0.05	2				
	No Load	$V_{I}(\overline{ENx}) = V_{I}(INx)$	$-40^{\circ}\text{C} \le \text{T}_{\text{J}} \le 125^{\circ}\text{C}$		2	20				μА
	on OUTx	V <sub>I</sub> (ENx) = 0 V	T <sub>J</sub> = 25°C					0.05	2	
			$-40^{\circ}C \le T_{J} \le 125^{\circ}C$						20	
Supply current, high-level output		$V_{I}(\overline{ENx}) = 0 V$	T <sub>J</sub> = 25°C		170	220				
	No Load		-40°C ≤ T <sub>J</sub> ≤ 125°C		200					
	on OUTx	$V_{I(ENx)} = V_{I(INx)}$	T <sub>J</sub> = 25°C					170	220	μΑ
			$-40^{\circ}C \le T_{J} \le 125^{\circ}C$					200		
I Leakage current L	OUTx connected		$-40^{\circ}C \le T_{J} \le 125^{\circ}C$		200					
	to ground		$-40^{\circ}C \le T_{J} \le 125^{\circ}C$					200		μА
Reverse leakage	IN = high	$V_{I(EN)} = 0 V$	T <sub>.1</sub> = 25°C		0.3					
current	impedance	$V_{I(EN)} = V_{I(IN)}$	1J=25 C					0.3		μА

#### undervoltage lockout

PARAMETER	TEST CONDITIONS	TF	TPS204xA		TPS205xA			UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNII
Low-level input voltage		2		2.5	2		2.5	V
Hysteresis	T <sub>J</sub> = 25°C		100			100		mV

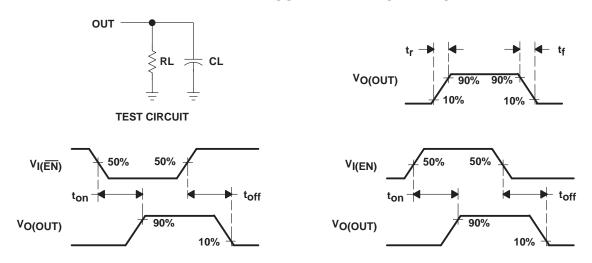
#### overcurrent OC

PARAMETER	TEST CONDITIONS	TI	PS204x	Α	TPS205xA			UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNII
Sink current <sup>†</sup>	V <sub>O</sub> = 5 V			10			10	mA
Output low voltage	$I_O = 5 \text{ V},  V_{OL(OC)}$			0.5			0.5	V
Off-state current <sup>†</sup>	$V_0 = 5 \text{ V},  V_0 = 3.3 \text{ V}$			1			1	μΑ

<sup>†</sup> Specified by design, not production tested.



#### PARAMETER MEASUREMENT INFORMATION



**VOLTAGE WAVEFORMS** 

Figure 1. Test Circuit and Voltage Waveforms

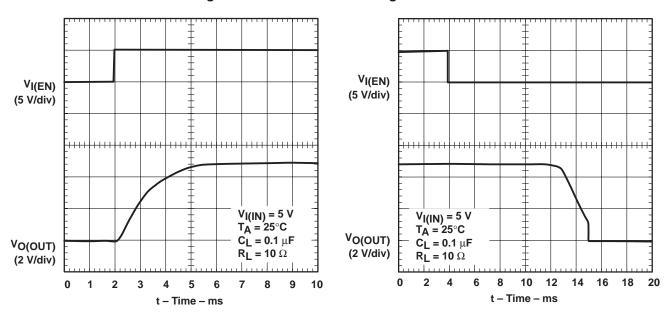


Figure 2. Turnon Delay and Rise Time with 0.1- $\mu$ F Load

Figure 3. Turnoff Delay and Fall Time with 0.1-μF Load

#### PARAMETER MEASUREMENT INFORMATION

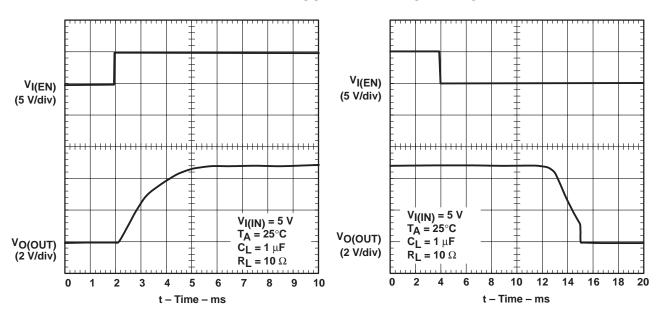


Figure 4. Turnon Delay and Rise Time with 1-μF Load

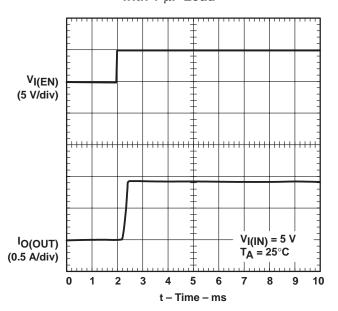


Figure 6. TPS2051A, Short-Circuit Current,
Device Enabled into Short

Figure 5. Turnoff Delay and Fall Time with 1-μF Load

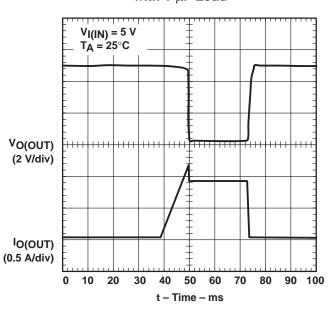


Figure 7. TPS2051A, Threshold Trip Current with Ramped Load on Enabled Device

#### PARAMETER MEASUREMENT INFORMATION

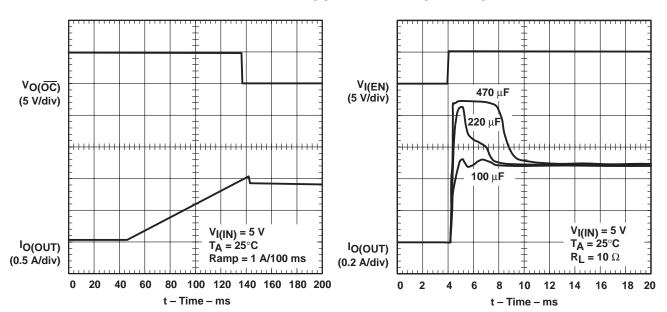


Figure 8. OC Response With Ramped Load on Enabled Device

Figure 9. Inrush Current with 100-μF, 220-μF and 470-μF Load Capacitance

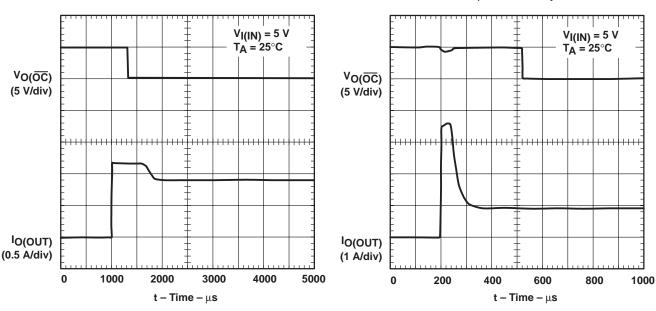


Figure 10. 4- $\Omega$  Load Connected to Enabled Device

Figure 11. 1- $\Omega$  Load Connected to Enabled Device

# **TYPICAL CHARACTERISTICS**

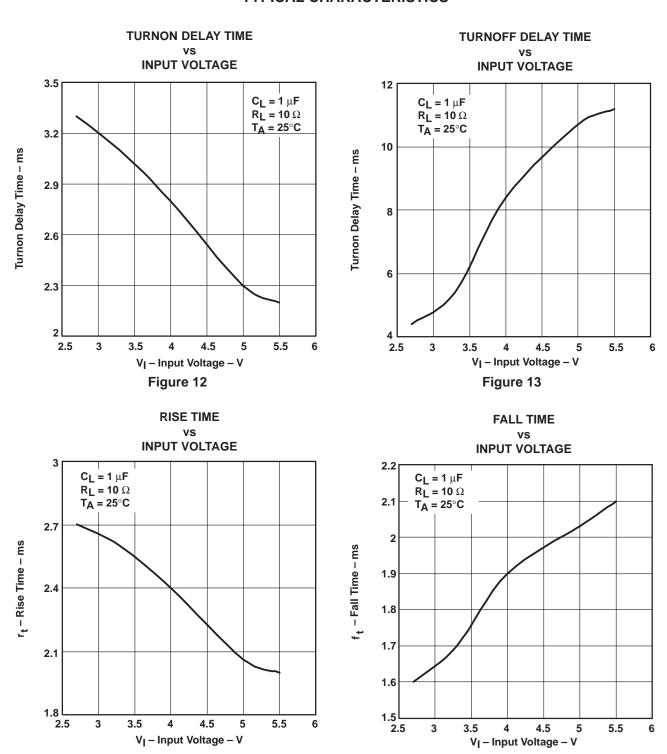


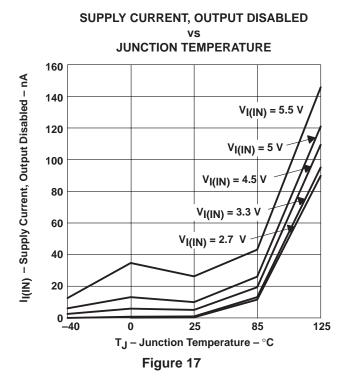


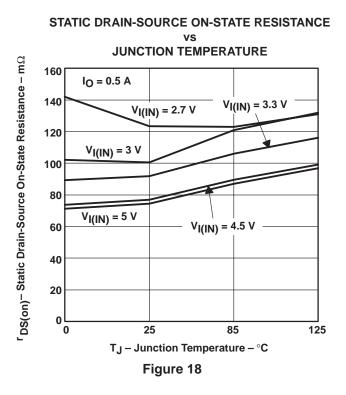
Figure 15

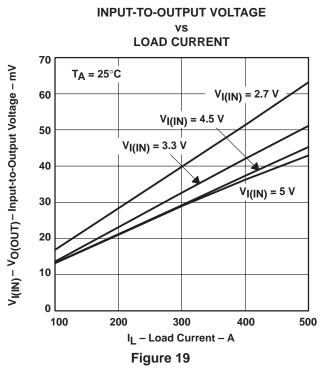
Figure 14

#### TYPICAL CHARACTERISTICS

# SUPPLY CURRENT, OUTPUT ENABLED JUNCTION TEMPERATURE 100 II(IN)– Supply Current, Output Enabled – $\mu$ A 90 $V_{I(IN)} = 5.5 V$ $V_{I(IN)} = 5 V$ 80 V<sub>I(IN)</sub> = 4.5 V 70 $V_{I(IN)} = 2.7 V$ 60 V<sub>I(IN)</sub> = 3.3 V 50 40 25 -40 85 125 T<sub>.</sub>I - Junction Temperature - °C Figure 16

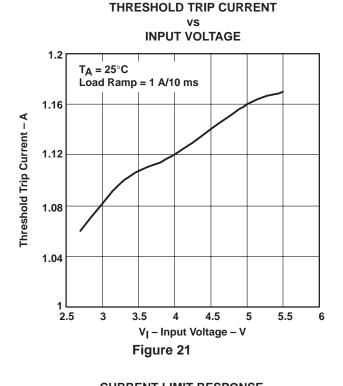


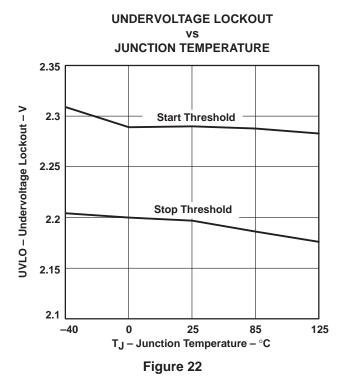


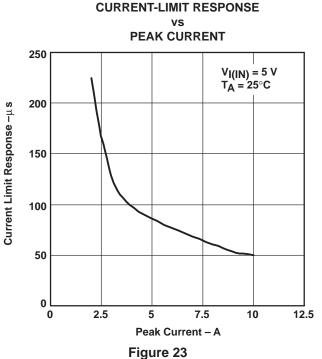


#### TYPICAL CHARACTERISTICS

# SHORT-CIRCUIT OUTPUT CURRENT **JUNCTION TEMPERATURE** 1.2 IOS - Short-circuit Output Current - A $V_{I(IN)} = 5.5 V$ 1.1 $V_{I(IN)} = 5 V$ $V_{I(IN)} = 4.5 V$ $V_{I(IN)} = 3.3 V$ 0.9 $V_{I(IN)} = 2.7 V$ 0.8 0.7 0.6 -40 25 85 125 T<sub>J</sub> – Junction Temperature – °C Figure 20







#### APPLICATION INFORMATION

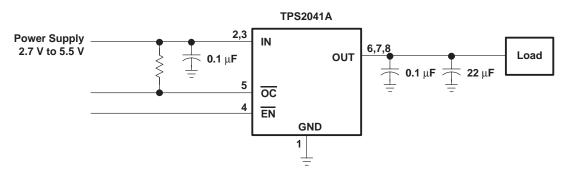


Figure 24. Typical Application (Example, TPS2041A)

#### power-supply considerations

A 0.01- $\mu F$  to 0.1- $\mu F$  ceramic bypass capacitor between INx and GND, close to the device, is recommended. Placing a high-value electrolytic capacitor on the output pin(s) is recommended when the output load is heavy. This precaution reduces power-supply transients that may cause ringing on the input. Additionally, bypassing the output with a 0.01- $\mu F$  to 0.1- $\mu F$  ceramic capacitor improves the immunity of the device to short-circuit transients.

#### overcurrent

A sense FET is employed to check for overcurrent conditions. Unlike current-sense resistors, sense FETs do not increase the series resistance of the current path. When an overcurrent condition is detected, the device maintains a constant output current and reduces the output voltage accordingly. Complete shutdown occurs only if the fault is present long enough to activate thermal limiting.

Three possible overload conditions can occur. In the first condition, the output has been shorted before the device is enabled or before  $V_{I(IN)}$  has been applied (see Figure 6). The TPS204xA and TPS205xA sense the short and immediately switch into a constant-current output.

In the second condition, a short or an overload occurs while the device is enabled. At the instant the overload occurs, very high currents may flow for a short time before the current-limit circuit can react. After the current-limit circuit has tripped (reached the overcurrent trip threshhold) the device switches into constant-current mode.

In the third condition, the load has been gradually increased beyond the recommended operating current. The current is permitted to rise until the current-limit threshold is reached or until the thermal limit of the device is exceeded (see Figure 7). The TPS204xA and TPS205xA are capable of delivering current up to the current-limit threshold without damaging the device. Once the threshold has been reached, the device switches into its constant-current mode.

# **OC** response

The  $\overline{\text{OC}}$  open-drain output is asserted (active low) when an overcurrent or overtemperature condition is encountered. The output will remain asserted until the overcurrent or overtemperature condition is removed. Connecting a heavy capacitive load to an enabled device can cause momentary false overcurrent reporting from the inrush current flowing through the device, charging the downstream capacitor. The TPS204xA and TPS205xA family of devices are designed to reduce false overcurrent reporting. An internal overcurrent transient filter eliminates the need for external components to remove unwanted pulses. Using low-ESR electrolytic capacitors on the output lowers the inrush current flow through the device during hot-plug events by providing a low-impedance energy source, also reducing erroneous overcurrent reporting.



#### APPLICATION INFORMATION

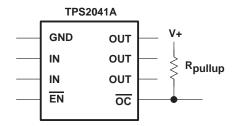


Figure 25. Typical Circuit for OC Pin (Example, TPS2041A)

# power dissipation and junction temperature

The low on-resistance on the n-channel MOSFET allows small surface-mount packages, such as SOIC, to pass large currents. The thermal resistances of these packages are high compared to those of power packages; it is good design practice to check power dissipation and junction temperature. Begin by determining the r<sub>DS(on)</sub> of the N-channel MOSFET relative to the input voltage and operating temperature. As an initial estimate, use the highest operating ambient temperature of interest and read r<sub>DS(on)</sub> from Figure 18. Using this value, the power dissipation per switch can be calcultaed by:

$$P_D = r_{DS(on)} \times I^2$$

Depending on which device is being used, multiply this number by the number of switches being used. This step will render the total power dissipation from the N-channel MOSFETs.

Finally, calculate the junction temperature:

$$T_{.I} = P_D \times R_{\theta.IA} + T_A$$

Where:

 $T_A$  = Ambient Temperature °C  $R_{\theta JA}$  = Thermal resistance SOIC = 172°C/W (for 8 pin), 111°C/W (for 16 pin)  $P_D$  = Total power dissipation based on number of switches being used.

Compare the calculated junction temperature with the initial estimate. If they do not agree within a few degrees, repeat the calculation, using the calculated value as the new estimate. Two or three iterations are generally sufficient to get a reasonable answer.

#### thermal protection

Thermal protection prevents damage to the IC when heavy-overload or short-circuit faults are present for extended periods of time. The faults force the TPS204xA and TPS205xA into constant-current mode, which causes the voltage across the high-side switch to increase; under short-circuit conditions, the voltage across the switch is equal to the input voltage. The increased dissipation causes the junction temperature to rise to high levels. The protection circuit senses the junction temperature of the switch and shuts it off. Hysteresis is built into the thermal sense circuit, and after the device has cooled approximately 20 degrees, the switch turns back on. The switch continues to cycle in this manner until the load fault or input power is removed.

The TPS204xA and TPS205xA implement a dual thermal trip to allow fully independent operation of the power distribution switches. In an overcurrent or short-circuit condition the junction temperature will rise. Once the die temperature rises to approximately 140°C, the internal thermal sense circuitry checks which power switch is in an overcurrent condition and turns that power switch off, thus isolating the fault without interrupting operation of the adjacent power switch. Should the die temperature exceed the first thermal trip point of 140°C and reach 160°C, both switches turn off. The OC open-drain output is asserted (active low) when overtemperature or overcurrent occurs.



#### **APPLICATION INFORMATION**

## undervoltage lockout (UVLO)

An undervoltage lockout ensures that the power switch is in the off state at power up. Whenever the input voltage falls below approximately 2 V, the power switch will be quickly turned off. This facilitates the design of hot-insertion systems where it is not possible to turn off the power switch before input power is removed. The UVLO will also keep the switch from being turned on until the power supply has reached at least 2 V, even if the switch is enabled. Upon reinsertion, the power switch will be turned on, with a controlled rise time to reduce EMI and voltage overshoots.

# universal serial bus (USB) applications

The universal serial bus (USB) interface is a 12-Mb/s, or 1.5-Mb/s, multiplexed serial bus designed for low-to-medium bandwidth PC peripherals (e.g., keyboards, printers, scanners, and mice). The four-wire USB interface is conceived for dynamic attach-detach (hot plug-unplug) of peripherals. Two lines are provided for differential data, and two lines are provided for 5-V power distribution.

USB data is a 3.3-V level signal, but power is distributed at 5 V to allow for voltage drops in cases where power is distributed through more than one hub across long cables. Each function must provide its own regulated 3.3 V from the 5-V input or its own internal power supply.

The USB specification defines the following five classes of devices, each differentiated by power-consumption requirements:

- Hosts/self-powered hubs (SPH)
- Bus-powered hubs (BPH)
- Low-power, bus-powered functions
- High-power, bus-powered functions
- Self-powered functions

Self-powered and bus-powered hubs distribute data and power to downstream functions. The TPS204xA and TPS205xA can provide power-distribution solutions for many of these classes of devices.

#### host/self-powered and bus-powered hubs

Hosts and self-powered hubs have a local power supply that powers the embedded functions and the downstream ports (see Figures 26 and 27). This power supply must provide from 5.25 V to 4.75 V to the board side of the downstream connection under full-load and no-load conditions. Hosts and SPHs are required to have current-limit protection and must report overcurrent conditions to the USB controller. Typical SPHs are desktop PCs, monitors, printers, and stand-alone hubs.

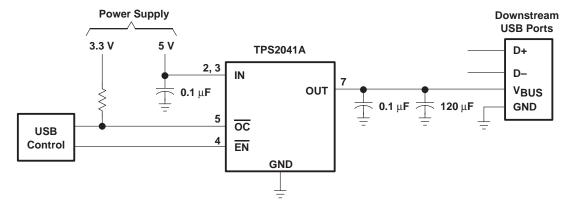


Figure 26. Typical One-Port Solution



#### APPLICATION INFORMATION

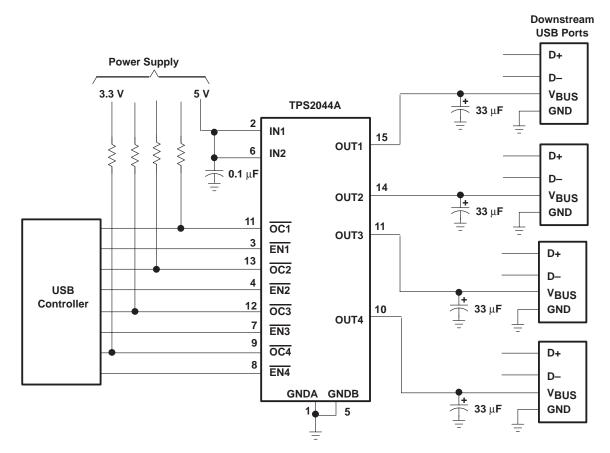


Figure 27. Typical Four-Port USB Host/Self-Powered Hub

Bus-powered hubs obtain all power from upstream ports and often contain an embedded function. The hubs are required to power up with less than one unit load. The BPH usually has one embedded function, and power is always available to the controller of the hub. If the embedded function and hub require more than 100 mA on powerup, the power to the embedded function may need to be kept off until enumeration is completed. This can be accomplished by removing power or by shutting off the clock to the embedded function. Power switching the embedded function is not necessary if the aggregate power draw for the function and controller is less than one unit load. The total current drawn by the bus-powered device is the sum of the current to the controller, the embedded function, and the downstream ports, and it is limited to 500 mA from an upstream port.



#### APPLICATION INFORMATION

# low-power bus-powered functions and high-power bus-powered functions

Both low-power and high-power bus-powered functions obtain all power from upstream ports; low-power functions always draw less than 100 mA; high-power functions must draw less than 100 mA at power up and can draw up to 500 mA after enumeration. If the load of the function is more than the parallel combination of  $44~\Omega$  and  $10~\mu$ F at power up, the device must implement inrush current limiting (see Figure 28).

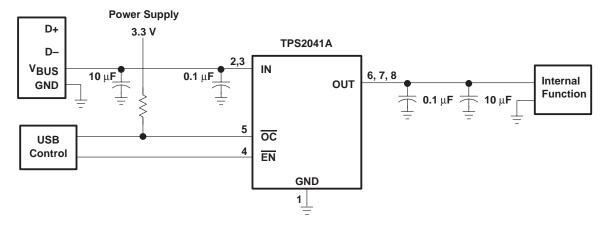


Figure 28. High-Power Bus-Powered Function (Example, TPS2041A)

# **USB** power-distribution requirements

USB can be implemented in several ways, and, regardless of the type of USB device being developed, several power-distribution features must be implemented.

- Hosts/self-powered hubs must:
  - Current-limit downstream ports
  - Report overcurrent conditions on USB V<sub>BUS</sub>
- Bus-powered hubs must:
  - Enable/disable power to downstream ports
  - Power up at <100 mA</li>
  - Limit inrush current ( $<44 \Omega$  and 10  $\mu$ F)
- Functions must:
  - Limit inrush currents
  - Power up at <100 mA</li>

The feature set of the TPS204xA and TPS205xA allows them to meet each of these requirements. The integrated current-limiting and overcurrent reporting is required by hosts and self-powered hubs. The logic-level enable and controlled rise times meet the need of both input and output ports on bus-power hubs, as well as the input ports for bus-power functions (see Figures 29 through 32).



#### APPLICATION INFORMATION

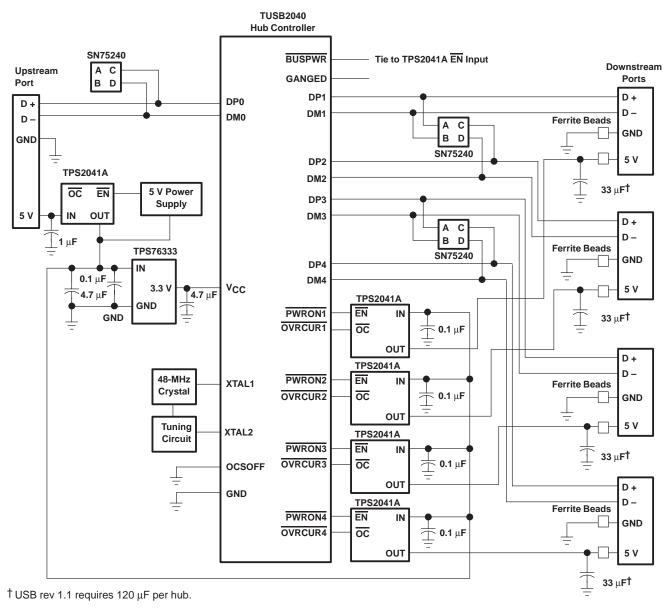


Figure 29. Hybrid Self/Bus-Powered Hub Implementation, TPS2041A



#### **APPLICATION INFORMATION**

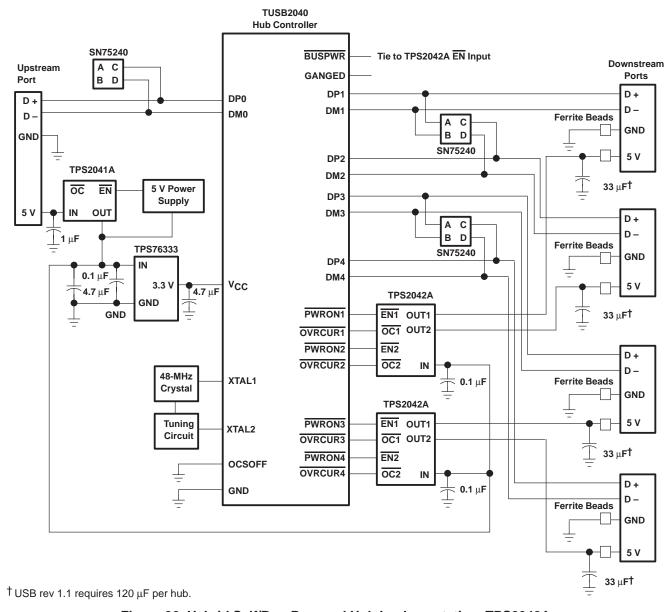
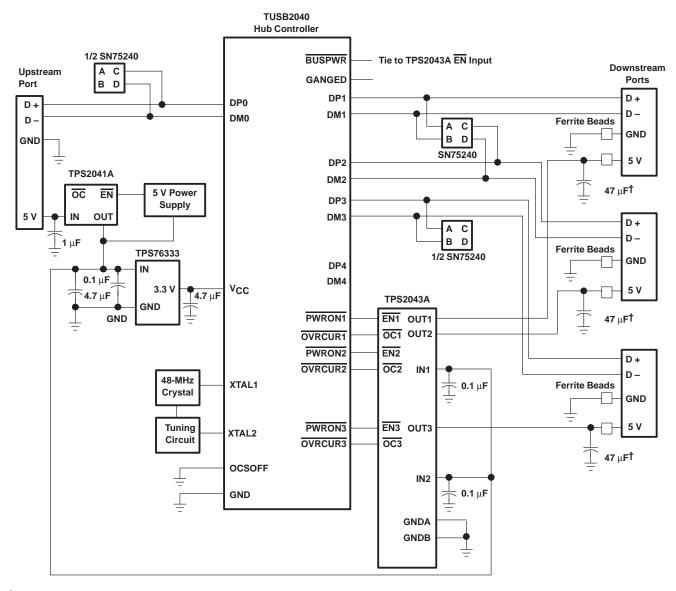


Figure 30. Hybrid Self/Bus-Powered Hub Implementation, TPS2042A

#### APPLICATION INFORMATION



† USB rev 1.1 requires 120 μF per hub.

Figure 31. Hybrid Self/Bus-Powered Hub Implementation, TPS2043A



#### **APPLICATION INFORMATION**

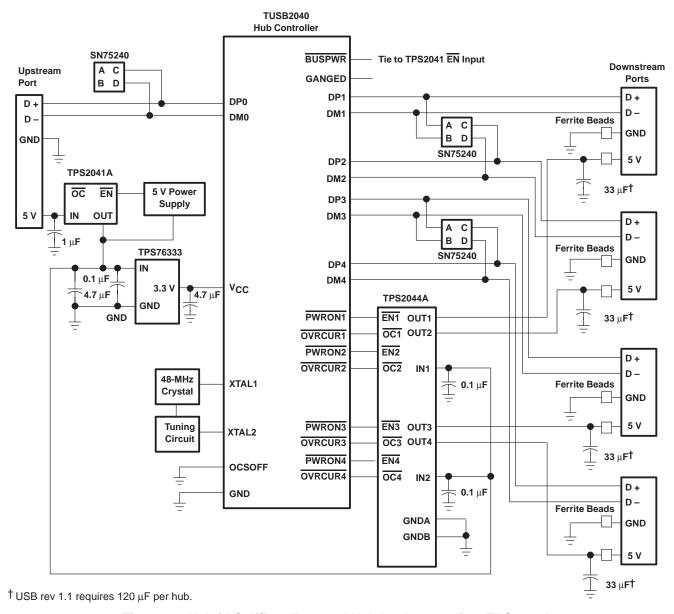


Figure 32. Hybrid Self/Bus-Powered Hub Implementation, TPS2044A

#### APPLICATION INFORMATION

## generic hot-plug applications (see Figure 33)

In many applications it may be necessary to remove modules or pc boards while the main unit is still operating. These are considered hot-plug applications. Such implementations require the control of current surges seen by the main power supply and the card being inserted. The most effective way to control these surges is to limit and slowly ramp the current and voltage being applied to the card, similar to the way in which a power supply normally turns on. Due to the controlled rise times and fall times of the TPS204xA and TPS205xA, these devices can be used to provide a softer start-up to devices being hot-plugged into a powered system. The UVLO feature of the TPS204xA and TPS205xA also ensures the switch will be off after the card has been removed, and the switch will be off during the next insertion. The UVLO feature insures a soft start with a controlled rise time for every insertion of the card or module.

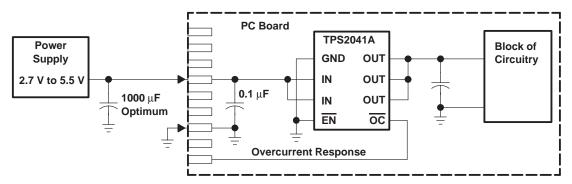


Figure 33. Typical Hot-Plug Implementation (Example, TPS2041A)

By placing the TPS204xA and TPS205xA between the  $V_{CC}$  input and the rest of the circuitry, the input power will reach these devices first after insertion. The typical rise time of the switch is approximately 2.5 ms, providing a slow voltage ramp at the output of the device. This implementation controls system surge currents and provides a hot-plugging mechanism for any device.

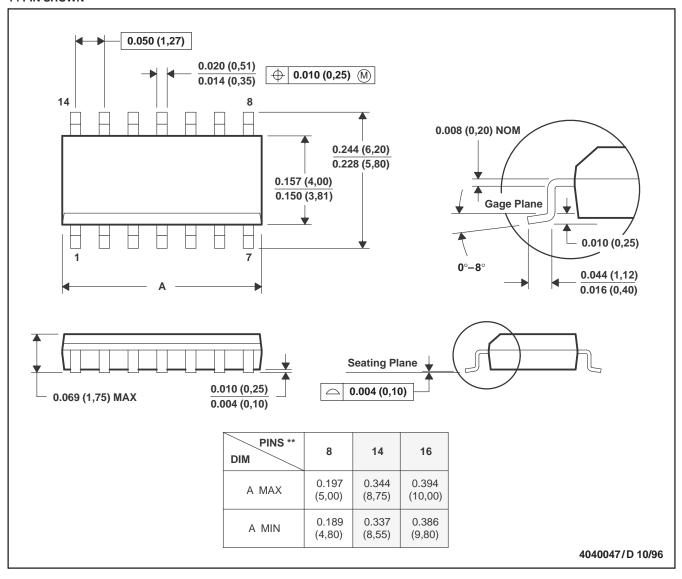


#### **MECHANICAL DATA**

# D (R-PDSO-G\*\*)

# 14 PIN SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

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